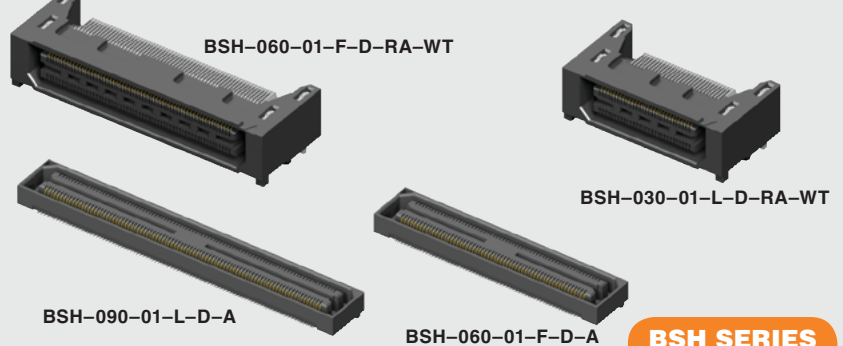




(0.50 mm) .0197"

**BSH SERIES**

# BASIC BLADE & BEAM SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?BSH](http://www.samtec.com?BSH)

### Insulator Material:

Black LCP

### Contact Material:

Phosphor Bronze

### Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

### Current Rating:

2 A per pin

(2 pins powered)

### Flammability Rating:

UL 94 VO

### Operating Temp Range:

-55 °C to +125 °C

### Voltage Rating:

275 VAC

### Max Cycles:

100

### RoHS Compliant:

Yes

## PROCESSING

### Lead-Free Solderable:

Yes

### SMT Lead Coplanarity:

(0.10 mm) .004" max (030-090)

(0.15 mm) .006" max (120-150)\*

\*(.004" stencil solution

may be available; contact

IPG@samtec.com)

### Board Stacking:

For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## ALSO AVAILABLE (MOQ Required)

- 30 μ" (0.76 μm) Gold
- Edge Mount Capability
- 8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)

Contact Samtec.

### Note:

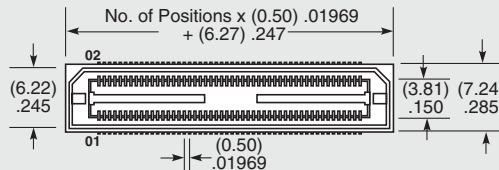
Some lengths, styles and options are non-standard, non-returnable.

BSH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
-----	--------------------------	----	----------------	---	---	--------------

Mates with:

BTH

-020, -040, -060, -090, -100, -120



## MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00) .197

\*Processing conditions will affect mated height.

-F  
= Gold Flash on contact, Matte Tin on tail

-L  
= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

-C\*  
= Electro-Polished Selective  
50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails

\*Note: -C Plating passes 10 year MFG testing

## POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

BSH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	RA	WT	OTHER OPTION
-----	--------------------------	----	----------------	---	----	----	--------------

Mates with:

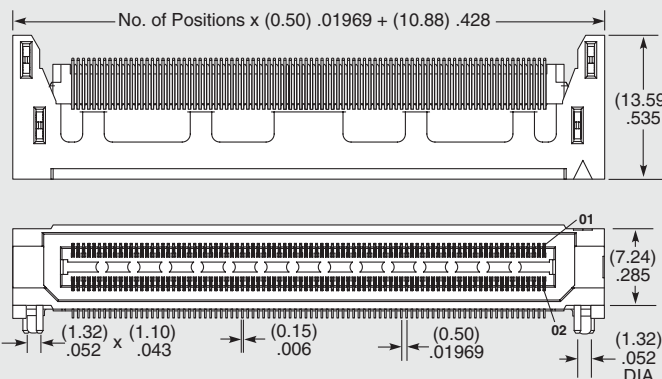
BTH

-030, -060, -090

-F  
= Gold Flash on contact, Matte Tin on tail

-L  
= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

-GP  
= Guide Post



Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.